



Toshiba Launches Photocopler with UVLO Function for Digitally Controlled Switching Power Supplies and IPM Drives

Long creepage distance and wide operating temperature range are ideal for demanding industrial applications

Düsseldorf, Germany, 19th March 2018 – Toshiba Electronics Europe today announced the launch of a new high-speed IC-Photocopler for MOSFET gate signal insulation. The TLP2735 is Toshiba's first photocopler to incorporate an under voltage lockout (UVLO) function with hysteresis.

UVLO reduces the photocoplers susceptibility to noise that is often generated in power supply cables, and can prevent malfunctions at switch on. With an isolation voltage of min. 5kVrms between the input and output, as well as compliance with the IEC60747-5-5 photocopler safety standard, the new TLP2735 is suitable for all applications that require high levels of insulation performance.

The operating power supply voltage in the output side covers the 9 to 20V range, ideally suited to MOSFET gate voltages. The high power supply voltage means that the device can also be used for IPM input insulation.

The TLP2735 offers a short propagation delay of 100ns (max) and a data transfer rate of 10Mbps.

The device is housed in a low profile SO6L surface mount package with a max. height of 2.3mm, that provides creepage and clearance distances of min. 8mm, supporting reinforced insulation requirements. In addition, with an operating temperature range of -40 to 125°C, the device is highly suited to rugged industrial applications.

The latest Gartner market report recognises Toshiba as the leading manufacturer of optocouplers by sales in 2015 and 2016, with 23% of sale-based market share in CY2016. (Source: Gartner, Inc. "Market Share: Semiconductor Devices and Applications, Worldwide, 2016" - 30 March 2017)

Toshiba will continue to deliver products that meet the needs of customers by promoting the development of a diverse portfolio of photocouplers and photorelays tailored to market trends.

###

About Toshiba Electronics Europe

[Toshiba Electronics Europe GmbH](#) (TEE) is the European electronic components business of [Toshiba Electronic Devices and Storage Corporation](#). TEE offers European consumers and businesses a wide variety of innovative hard disk drive (HDD) products plus semiconductor solutions for automotive, industrial, IoT, motion control, telecoms, networking, consumer and white goods applications. The company's broad portfolio encompasses integrated wireless ICs, power semiconductors, microcontrollers, optical semiconductors, ASICs, ASSPs and discrete devices ranging from diodes to logic ICs.

Formed in 1973 in Neuss, Germany, TEE has headquarters in Düsseldorf, Germany, with branch offices in Germany, France, Italy, Spain, Sweden and the United Kingdom providing design, manufacturing, marketing and sales. Company president is Mr. Akira Morinaga.

For more company information visit TEE's web site at www.toshiba.semicon-storage.com.

Contact details for publication:

Toshiba Electronics Europe GmbH, Hansaallee 181, D-40549 Düsseldorf, Germany

Tel: +49 (0) 211 5296 0 Fax: +49 (0) 211 5296 79197

Web: www.toshiba.semicon-storage.com/eu/company/news.html

E-mail: discrete-ic@toshiba-components.com

Contact details for editorial enquiries:

Michelle Shrimpton, Toshiba Electronics Europe GmbH

Tel: +44 (0)193 282 2832

E-mail: MShrimpton@teu.toshiba.de

Issued by:

Birgit Schöniger, Publitek

Tel: +44 (0) 20 8429 6554

Web: www.publitek.com

E-mail: birgit.schoeniger@publitek.com

March 2018 Ref. 7085/A